ASSOCIATION CONNECTION ELECTRONICS INDUSTRIES	Material Compos © Copyright 2005. IPC international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ous Materia	ials and Mfg Information			
upplier Inforn	nation														
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
nsemi												2023-06-08			
Contact Name		Title - Contact			F	Phone - Contact*					Email - Contact*				
Product-Env-Stew	ards		Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com			
uthorized Repres	entative*		Title - Representative			F	Phone - Representative*				Email - Representative*				
Product-Env-Stew	ards	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com					
Request	Requester Item Number Mfr		Item Number Mfr Item Name				Effective Date	e Vers	sion	Manufacturing Site		V	Veight*	UOM	Unit Type
		NCP133A	MX120TCG	500mA VLDO Bia option, Vout=1.20	as Rail CMOS Vre	eg, AD	2023-06-08			MY1		1	.84	mg	Each
Ianufacturing	Process Information	on													
Terminal Plating / Grid Array Material To			Germinal Base Alloy J-STD-020 MSL		-STD-020 MSL Ra	ating	Peak Process Body Temperature Max Time at Pe			me at Peak	ak Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed			CU Alloy 1			260	260 C 30			seconds 3					
omments															
vel 1 - maximum	time at peak temperature	e during solo	dering is 10-3	0 seconds										·	
or more informati	ion regarding material co	mposition p	lease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.09	mg	Supplier	Silicon (Si)	7440-21-3		0.09	mg
Die Attach Epoxy	0.015	mg		Epoxy resin	proprietary data		0.0015	mg
			Supplier	Cumene hydroperoxide	80-15-9		0.0001	mg
			Supplier	Diethylene glycol monoethyl ether acetate	112-15-2		0.0007	mg
			Supplier	Silver (Ag)	7440-22-4		0.0127	mg
Lead Frame	0.82	mg	Supplier	Silver (Ag)	7440-22-4		0.0328	mg
			Supplier	Tin (Sn)	7440-31-5		0.0021	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0018	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0021	mg
			Supplier	Copper (Cu)	7440-50-8		0.7813	mg
Mold Compound-Black	0.88	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.0704	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0044	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0176	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.7612	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0264	mg
Plating	0.02	mg	Supplier	Tin (Sn)	7440-31-5		0.02	mg
Wire Bond	0.015	mg	Supplier	Palladium (Pd)	7440-05-3		0.0003	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0147	mg